

1.8mm TRI-LEVEL LED INDICATOR

Part Number: WP406A10XHA/3ID

High Efficiency Red

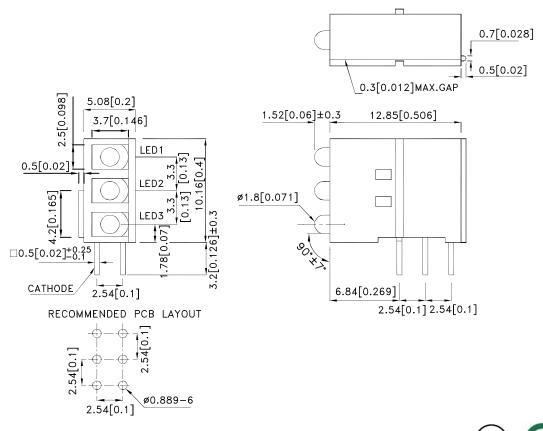
Features

- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the lead emerge from the package.

 4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Тур.	201/2
WP406A10XHA/3ID	High Efficiency Red (GaAsP/GaP)	Dad Differend	8	15	70°
		Red Diffused	*4	*8	

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.		Max.	Units	Test Conditions
λpeak	Peak Wavelength	High Efficiency Red	627	*627		nm	IF=20mA
λD [1]	Dominant Wavelength	High Efficiency Red	625	*617		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	High Efficiency Red	45			nm	IF=20mA
С	Capacitance	High Efficiency Red	15			pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	High Efficiency Red	2		2.5	V	IF=20mA
lR	Reverse Current	High Efficiency Red			10	uA	VR = 5V

Notes:

Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	160	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

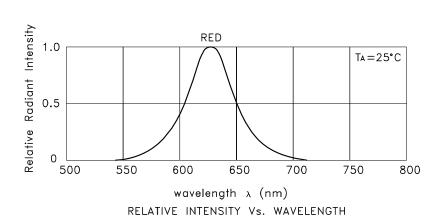
Notes:

- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
 2. 2mm below package base.
 3. 5mm below package base.

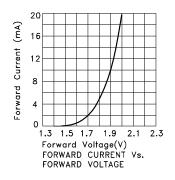
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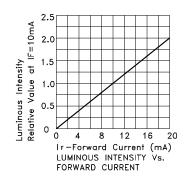
Luminous intensity/ luminous Flux: +/-15%.
 *Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

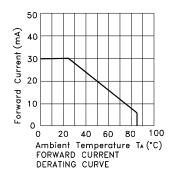
^{1.} Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.
*Wavelength value is traceable to the CIE127-2007 compliant national standards.

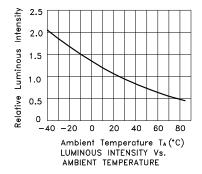


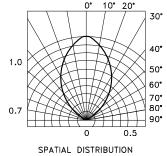
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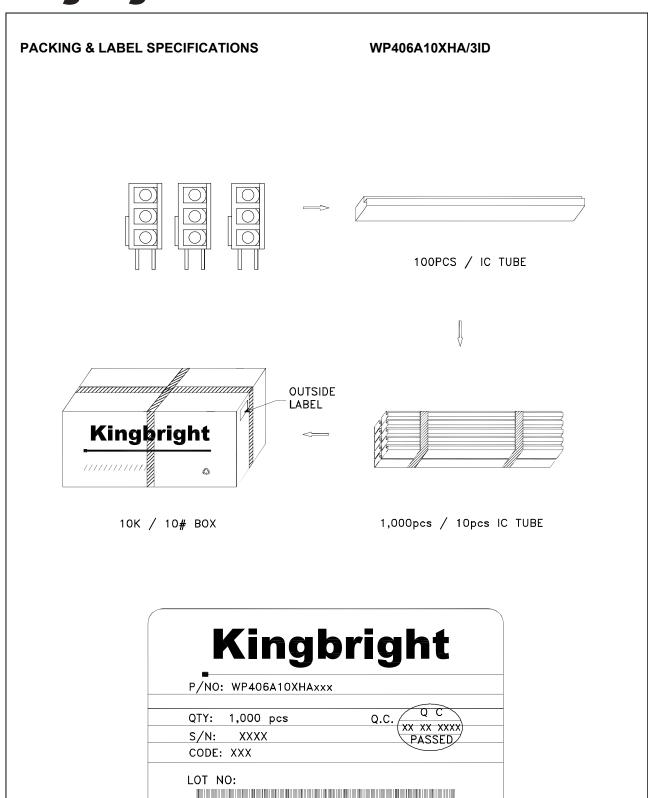






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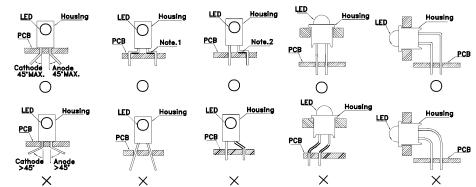
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RoHS Compliant

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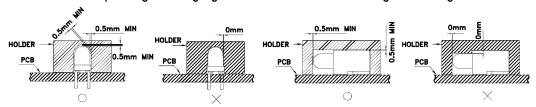
PRECAUTIONS

 The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

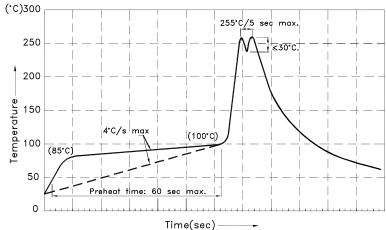


" \bigcirc " Correct mounting method "imes" Incorrect mounting method

2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through—hole LEDs are incompatible with reflow soldering.
- 5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 6. Recommended Wave Soldering Profiles:



1.Recommend pre—heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C

2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above 85°C.

4.Fixtures should not incur stress on the component when mounting and during soldering process.

5.SAC 305 solder alloy is recommended.

6.No more than one wave soldering pass.

All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

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